Icemos Technology Ltd Product Specification 1003.655701 Issue Date 07 February 2018 12:0

Part Number (7
Part Number (Customer

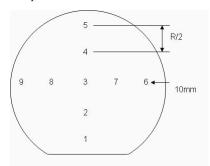
Category	Parameter		Specification	Measurement Method
OverallWafer	1.0	Diameter	150.00 +/- 0.20 mm	
	2.0	Primary Flat Orientation	{110}+/- 0.5 degree	Wafer Vendor
	3.0	Primary Flat Length	57.50 +/- 2.50 mm	Wafer Vendor
	4.0	Secondary Flat Orientation	none	
	5.0	Overall Thickness	380.00 +/- 10.00 μm	ADE, 100%
	6.0	Total Thickness Variation (TTV)	<5.00μm	Guaranteed by Process
	7.0	Bow	<20.00μm	ADE to ASTM F534, 20%
	8.0	Warp	<20.00μm	ADE to ASTM F657, 20%
	9.0	Edge Chips	<30um / Wafer edge polishgd or fine ground (No cracks)	Bright Light, 100% (note 2)
	10.0	Edge Exclusion	5mm	
	11.0	Frontsurface condition	Polished, surface roughness <1nm rms.	
	12.0	Flatness (SBIR)	<1um, 25mm X 25mm. No partials.	
	13.0	Front Surface Quality	No Particles >10um	
HandleSilicon	14.0	Handle Silicon Raw Material	Prime Silicon	
	15.0	Handle Growth Method	CZ	Wafer Vendor
	16.0	Handle Orientation	{100} +/- 1.0 degree	Wafer Vendor
	17.0	Handle Thickness	380.00 +/- 10.00 μm	ADE, 100%
	18.0	Handle Doping Type	P	Wafer Vendor
	19.0	Handle Dopant	Boron	Wafer Vendor
	20.0	Handle Resistivity	>10 Ohmcm	Wafer Vendor
	21.0	Backside Finish	Polished, no lasermarking. Surface roughness <1nm rms. Light handling scrtaches.	Wafer Vendor
	22.0	Surface Haze	none	Bright Light, 100% (note 2)

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Part Number		Customer	
Category	Parameter	Specification	Measurement Method
Shipping Details	Wafer per box :	Max 25	
	Packaging:	Taped Polypropylene Wafer Box Empak, Ultrapak, 150.00mm Antistatic Double Bagging	
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness	
Explanatory Notes	1. Microscope inspec	tion performed using microscope scan as below. 5x objective.	
		pections performed exclude all wafer area outside the edge exclusio	on defined in Overall

Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information